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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	448
Number of Logic Elements/Cells	4032
Total RAM Bits	294912
Number of I/O	68
Number of Gates	200000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-TQFP
Supplier Device Package	100-VQFP (14x14)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/xilinx/xc3s200a-5vqg100c">https://www.e-xfl.com/product-detail/xilinx/xc3s200a-5vqg100c</a>



## Introduction

The Spartan®-3A family of Field-Programmable Gate Arrays (FPGAs) solves the design challenges in most high-volume, cost-sensitive, I/O-intensive electronic applications. The five-member family offers densities ranging from 50,000 to 1.4 million system gates, as shown in [Table 1](#).

The Spartan-3A FPGAs are part of the Extended Spartan-3A family, which also include the non-volatile Spartan-3AN and the higher density Spartan-3A DSP FPGAs. The Spartan-3A family builds on the success of the earlier Spartan-3E and Spartan-3 FPGA families. New features improve system performance and reduce the cost of configuration. These Spartan-3A family enhancements, combined with proven 90 nm process technology, deliver more functionality and bandwidth per dollar than ever before, setting the new standard in the programmable logic industry.

Because of their exceptionally low cost, Spartan-3A FPGAs are ideally suited to a wide range of consumer electronics applications, including broadband access, home networking, display/projection, and digital television equipment.

The Spartan-3A family is a superior alternative to mask programmed ASICs. FPGAs avoid the high initial cost, lengthy development cycles, and the inherent inflexibility of conventional ASICs, and permit field design upgrades.

## Features

- Very low cost, high-performance logic solution for high-volume, cost-conscious applications
- Dual-range  $V_{CCAUX}$  supply simplifies 3.3V-only design
- Suspend, Hibernate modes reduce system power
- Multi-voltage, multi-standard SelectIO™ interface pins
  - Up to 502 I/O pins or 227 differential signal pairs
  - LVCMOS, LVTTTL, HSTL, and SSTL single-ended I/O
  - 3.3V, 2.5V, 1.8V, 1.5V, and 1.2V signaling
  - Selectable output drive, up to 24 mA per pin
  - QUIETIO standard reduces I/O switching noise
  - Full 3.3V ± 10% compatibility and hot swap compliance

- 640+ Mb/s data transfer rate per differential I/O
- LVDS, RSDS, mini-LVDS, HSTL/SSTL differential I/O with integrated differential termination resistors
- Enhanced Double Data Rate (DDR) support
- DDR/DDR2 SDRAM support up to 400 Mb/s
- Fully compliant 32-/64-bit, 33/66 MHz PCI® technology support
- Abundant, flexible logic resources
  - Densities up to 25,344 logic cells, including optional shift register or distributed RAM support
  - Efficient wide multiplexers, wide logic
  - Fast look-ahead carry logic
  - Enhanced 18 x 18 multipliers with optional pipeline
  - IEEE 1149.1/1532 JTAG programming/debug port
- Hierarchical SelectRAM™ memory architecture
  - Up to 576 Kbits of fast block RAM with byte write enables for processor applications
  - Up to 176 Kbits of efficient distributed RAM
- Up to eight Digital Clock Managers (DCMs)
  - Clock skew elimination (delay locked loop)
  - Frequency synthesis, multiplication, division
  - High-resolution phase shifting
  - Wide frequency range (5 MHz to over 320 MHz)
- Eight low-skew global clock networks, eight additional clocks per half device, plus abundant low-skew routing
- Configuration interface to industry-standard PROMs
  - Low-cost, space-saving SPI serial Flash PROM
  - x8 or x8/x16 BPI parallel NOR Flash PROM
  - Low-cost Xilinx® Platform Flash with JTAG
  - Unique Device DNA identifier for design authentication
  - Load multiple bitstreams under FPGA control
  - Post-configuration CRC checking
- Complete Xilinx ISE® and WebPACK™ development system software support plus [Spartan-3A Starter Kit](#)
- [MicroBlaze™](#) and [PicoBlaze™](#) embedded processors
- Low-cost QFP and BGA packaging, Pb-free options
  - Common footprints support easy density migration
  - Compatible with select [Spartan-3AN](#) nonvolatile FPGAs
  - Compatible with higher density [Spartan-3A DSP](#) FPGAs
- [XA Automotive](#) version available

Table 1: Summary of Spartan-3A FPGA Attributes

Device	System Gates	Equivalent Logic Cells	CLB Array (One CLB = Four Slices)				Distributed RAM bits <sup>(1)</sup>	Block RAM bits <sup>(1)</sup>	Dedicated Multipliers	DCMs	Maximum User I/O	Maximum Differential I/O Pairs
			Rows	Columns	CLBs	Slices						
XC3S50A	50K	1,584	16	12	176	704	11K	54K	3	2	144	64
XC3S200A	200K	4,032	32	16	448	1,792	28K	288K	16	4	248	112
XC3S400A	400K	8,064	40	24	896	3,584	56K	360K	20	4	311	142
XC3S700A	700K	13,248	48	32	1,472	5,888	92K	360K	20	8	372	165
XC3S1400A	1400K	25,344	72	40	2,816	11,264	176K	576K	32	8	502	227

### Notes:

1. By convention, one Kb is equivalent to 1,024 bits.

## Power Supply Specifications

**Table 5: Supply Voltage Thresholds for Power-On Reset**

Symbol	Description	Min	Max	Units
$V_{CCINTT}$	Threshold for the $V_{CCINT}$ supply	0.4	1.0	V
$V_{CCAUXT}$	Threshold for the $V_{CCAUX}$ supply	1.0	2.0	V
$V_{CCO2T}$	Threshold for the $V_{CCO}$ Bank 2 supply	1.0	2.0	V

**Notes:**

- $V_{CCINT}$ ,  $V_{CCAUX}$ , and  $V_{CCO}$  supplies to the FPGA can be applied in any order. However, the FPGA's configuration source (Platform Flash, SPI Flash, parallel NOR Flash, microcontroller) might have specific requirements. Check the data sheet for the attached configuration source. Apply  $V_{CCINT}$  last for lowest overall power consumption (see [UG331](#) chapter "Powering Spartan-3 Generation FPGAs" for more information).
- To ensure successful power-on,  $V_{CCINT}$ ,  $V_{CCO}$  Bank 2, and  $V_{CCAUX}$  supplies must rise through their respective threshold-voltage ranges with no dips at any point.

**Table 6: Supply Voltage Ramp Rate**

Symbol	Description	Min	Max	Units
$V_{CCINTR}$	Ramp rate from GND to valid $V_{CCINT}$ supply level	0.2	100	ms
$V_{CCAUXR}$	Ramp rate from GND to valid $V_{CCAUX}$ supply level	0.2	100	ms
$V_{CCO2R}$	Ramp rate from GND to valid $V_{CCO}$ Bank 2 supply level	0.2	100	ms

**Notes:**

- $V_{CCINT}$ ,  $V_{CCAUX}$ , and  $V_{CCO}$  supplies to the FPGA can be applied in any order. However, the FPGA's configuration source (Platform Flash, SPI Flash, parallel NOR Flash, microcontroller) might have specific requirements. Check the data sheet for the attached configuration source. Apply  $V_{CCINT}$  last for lowest overall power consumption (see [UG331](#) chapter "Powering Spartan-3 Generation FPGAs" for more information).
- To ensure successful power-on,  $V_{CCINT}$ ,  $V_{CCO}$  Bank 2, and  $V_{CCAUX}$  supplies must rise through their respective threshold-voltage ranges with no dips at any point.

**Table 7: Supply Voltage Levels Necessary for Preserving CMOS Configuration Latch (CCL) Contents and RAM Data**

Symbol	Description	Min	Units
$V_{DRINT}$	$V_{CCINT}$ level required to retain CMOS Configuration Latch (CCL) and RAM data	1.0	V
$V_{DRAUX}$	$V_{CCAUX}$ level required to retain CMOS Configuration Latch (CCL) and RAM data	2.0	V

## General DC Characteristics for I/O Pins

Table 9: General DC Characteristics of User I/O, Dual-Purpose, and Dedicated Pins<sup>(1)</sup>

Symbol	Description	Test Conditions		Min	Typ	Max	Units
$I_L^{(2)}$	Leakage current at User I/O, input-only, dual-purpose, and dedicated pins, FPGA powered	Driver is in a high-impedance state, $V_{IN} = 0V$ or $V_{CCO}$ max, sample-tested		-10	-	+10	$\mu A$
$I_{HS}$	Leakage current on pins during hot socketing, FPGA unpowered	All pins except INIT_B, PROG_B, DONE, and JTAG pins when PUDC_B = 1.		-10	-	+10	$\mu A$
		INIT_B, PROG_B, DONE, and JTAG pins or other pins when PUDC_B = 0.		Add $I_{HS} + I_{RPU}$			$\mu A$
$I_{RPU}^{(3)}$	Current through pull-up resistor at User I/O, dual-purpose, input-only, and dedicated pins. Dedicated pins are powered by $V_{CCAUX}$ .	$V_{IN} = GND$	$V_{CCO}$ or $V_{CCAUX} = 3.0V$ to $3.6V$	-151	-315	-710	$\mu A$
			$V_{CCO}$ or $V_{CCAUX} = 2.3V$ to $2.7V$	-82	-182	-437	$\mu A$
			$V_{CCO} = 1.7V$ to $1.9V$	-36	-88	-226	$\mu A$
			$V_{CCO} = 1.4V$ to $1.6V$	-22	-56	-148	$\mu A$
			$V_{CCO} = 1.14V$ to $1.26V$	-11	-31	-83	$\mu A$
$R_{PU}^{(3)}$	Equivalent pull-up resistor value at User I/O, dual-purpose, input-only, and dedicated pins (based on $I_{RPU}$ per Note 3)	$V_{IN} = GND$	$V_{CCO} = 3.0V$ to $3.6V$	5.1	11.4	23.9	$k\Omega$
			$V_{CCO} = 2.3V$ to $2.7V$	6.2	14.8	33.1	$k\Omega$
			$V_{CCO} = 1.7V$ to $1.9V$	8.4	21.6	52.6	$k\Omega$
			$V_{CCO} = 1.4V$ to $1.6V$	10.8	28.4	74.0	$k\Omega$
			$V_{CCO} = 1.14V$ to $1.26V$	15.3	41.1	119.4	$k\Omega$
$I_{RPD}^{(3)}$	Current through pull-down resistor at User I/O, dual-purpose, input-only, and dedicated pins. Dedicated pins are powered by $V_{CCAUX}$ .	$V_{IN} = V_{CCO}$	$V_{CCAUX} = 3.0V$ to $3.6V$	167	346	659	$\mu A$
			$V_{CCAUX} = 2.25V$ to $2.75V$	100	225	457	$\mu A$
$R_{PD}^{(3)}$	Equivalent pull-down resistor value at User I/O, dual-purpose, input-only, and dedicated pins (based on $I_{RPD}$ per Note 3)	$V_{CCAUX} = 3.0V$ to $3.6V$	$V_{IN} = 3.0V$ to $3.6V$	5.5	10.4	20.8	$k\Omega$
			$V_{IN} = 2.3V$ to $2.7V$	4.1	7.8	15.7	$k\Omega$
			$V_{IN} = 1.7V$ to $1.9V$	3.0	5.7	11.1	$k\Omega$
			$V_{IN} = 1.4V$ to $1.6V$	2.7	5.1	9.6	$k\Omega$
			$V_{IN} = 1.14V$ to $1.26V$	2.4	4.5	8.1	$k\Omega$
		$V_{CCAUX} = 2.25V$ to $2.75V$	$V_{IN} = 3.0V$ to $3.6V$	7.9	16.0	35.0	$k\Omega$
			$V_{IN} = 2.3V$ to $2.7V$	5.9	12.0	26.3	$k\Omega$
			$V_{IN} = 1.7V$ to $1.9V$	4.2	8.5	18.6	$k\Omega$
			$V_{IN} = 1.4V$ to $1.6V$	3.6	7.2	15.7	$k\Omega$
			$V_{IN} = 1.14V$ to $1.26V$	3.0	6.0	12.5	$k\Omega$
$I_{REF}$	$V_{REF}$ current per pin	All $V_{CCO}$ levels		-10	-	+10	$\mu A$
$C_{IN}$	Input capacitance	-		-	-	10	pF
$R_{DT}$	Resistance of optional differential termination circuit within a differential I/O pair. Not available on Input-only pairs.	$V_{CCO} = 3.3V \pm 10\%$	LVDS_33, MINI_LVDS_33, RSDS_33	90	100	115	$\Omega$
		$V_{CCO} = 2.5V \pm 10\%$	LVDS_25, MINI_LVDS_25, RSDS_25	90	110	-	$\Omega$

## Notes:

- The numbers in this table are based on the conditions set forth in Table 8.
- For single-ended signals that are placed on a differential-capable I/O,  $V_{IN}$  of  $-0.2V$  to  $-0.5V$  is supported but can cause increased leakage between the two pins. See "Parasitic Leakage" in UG331, *Spartan-3 Generation FPGA User Guide*.
- This parameter is based on characterization. The pull-up resistance  $R_{PU} = V_{CCO} / I_{RPU}$ . The pull-down resistance  $R_{PD} = V_{IN} / I_{RPD}$ .

## Quiescent Current Requirements

Table 10: Quiescent Supply Current Characteristics

Symbol	Description	Device	Typical <sup>(2)</sup>	Commercial Maximum <sup>(2)</sup>	Industrial Maximum <sup>(2)</sup>	Units
I <sub>CCINTQ</sub>	Quiescent V <sub>CCINT</sub> supply current	XC3S50A	2	20	30	mA
		XC3S200A	7	50	70	mA
		XC3S400A	10	85	125	mA
		XC3S700A	13	120	185	mA
		XC3S1400A	24	220	310	mA
I <sub>CCOQ</sub>	Quiescent V <sub>CCO</sub> supply current	XC3S50A	0.2	2	3	mA
		XC3S200A	0.2	2	3	mA
		XC3S400A	0.3	3	4	mA
		XC3S700A	0.3	3	4	mA
		XC3S1400A	0.3	3	4	mA
I <sub>CCAUXQ</sub>	Quiescent V <sub>CCAUX</sub> supply current	XC3S50A	3	8	10	mA
		XC3S200A	5	12	15	mA
		XC3S400A	5	18	24	mA
		XC3S700A	6	28	34	mA
		XC3S1400A	10	50	58	mA

### Notes:

- The numbers in this table are based on the conditions set forth in [Table 8](#).
- Quiescent supply current is measured with all I/O drivers in a high-impedance state and with all pull-up/pull-down resistors at the I/O pads disabled. Typical values are characterized using typical devices at room temperature (T<sub>J</sub> of 25°C at V<sub>CCINT</sub> = 1.2V, V<sub>CCO</sub> = 3.3V, and V<sub>CCAUX</sub> = 2.5V). The maximum limits are tested for each device at the respective maximum specified junction temperature and at maximum voltage limits with V<sub>CCINT</sub> = 1.26V, V<sub>CCO</sub> = 3.6V, and V<sub>CCAUX</sub> = 3.6V. The FPGA is programmed with a “blank” configuration data file (that is, a design with no functional elements instantiated). For conditions other than those described above (for example, a design including functional elements), measured quiescent current levels will be different than the values in the table.
- For more accurate estimates for a specific design, use the Xilinx XPower tools. There are two recommended ways to estimate the total power consumption (quiescent plus dynamic) for a specific design: a) The [Spartan-3A FPGA XPower Estimator](#) provides quick, approximate, typical estimates, and does not require a netlist of the design. b) XPower Analyzer uses a netlist as input to provide maximum estimates as well as more accurate typical estimates.
- The maximum numbers in this table indicate the minimum current each power rail requires in order for the FPGA to power-on successfully.
- For information on the power-saving Suspend mode, see [XAPP480: Using Suspend Mode in Spartan-3 Generation FPGAs](#). Suspend mode typically saves 40% total power consumption compared to quiescent current.

## I/O Timing

### Pin-to-Pin Clock-to-Output Times

Table 18: Pin-to-Pin Clock-to-Output Times for the IOB Output Path

Symbol	Description	Conditions	Device	Speed Grade		Units
				-5	-4	
				Max	Max	
<b>Clock-to-Output Times</b>						
T <sub>ICKOFDCM</sub>	When reading from the Output Flip-Flop (OFF), the time from the active transition on the Global Clock pin to data appearing at the Output pin. The DCM is in use.	LVCMOS25 <sup>(2)</sup> , 12mA output drive, Fast slew rate, with DCM <sup>(3)</sup>	XC3S50A	3.18	3.42	ns
			XC3S200A	3.21	3.27	ns
			XC3S400A	2.97	3.33	ns
			XC3S700A	3.39	3.50	ns
			XC3S1400A	3.51	3.99	ns
T <sub>ICKOF</sub>	When reading from OFF, the time from the active transition on the Global Clock pin to data appearing at the Output pin. The DCM is not in use.	LVCMOS25 <sup>(2)</sup> , 12mA output drive, Fast slew rate, without DCM	XC3S50A	4.59	5.02	ns
			XC3S200A	4.88	5.24	ns
			XC3S400A	4.68	5.12	ns
			XC3S700A	4.97	5.34	ns
			XC3S1400A	5.06	5.69	ns

#### Notes:

1. The numbers in this table are tested using the methodology presented in [Table 27](#) and are based on the operating conditions set forth in [Table 8](#) and [Table 11](#).
2. This clock-to-output time requires adjustment whenever a signal standard other than LVCMOS25 is assigned to the Global Clock Input or a standard other than LVCMOS25 with 12 mA drive and Fast slew rate is assigned to the data Output. If the former is true, *add* the appropriate Input adjustment from [Table 23](#). If the latter is true, *add* the appropriate Output adjustment from [Table 26](#).
3. DCM output jitter is included in all measurements.

## Input Setup and Hold Times

Table 20: Setup and Hold Times for the IOB Input Path

Symbol	Description	Conditions	IFD_ DELAY_ VALUE	Device	Speed Grade		Units
					-5	-4	
					Min	Min	
<b>Setup Times</b>							
T <sub>IOPICK</sub>	Time from the setup of data at the Input pin to the active transition at the ICLK input of the Input Flip-Flop (IFF). No Input Delay is programmed.	LVCMOS25 <sup>(2)</sup>	0	XC3S50A	1.56	1.58	ns
				XC3S200A	1.71	1.81	ns
				XC3S400A	1.30	1.51	ns
				XC3S700A	1.34	1.51	ns
				XC3S1400A	1.36	1.74	ns
T <sub>IOPICKD</sub>	Time from the setup of data at the Input pin to the active transition at the ICLK input of the Input Flip-Flop (IFF). The Input Delay is programmed.	LVCMOS25 <sup>(2)</sup>	1	XC3S50A	2.16	2.18	ns
				2	3.10	3.12	ns
				3	3.51	3.76	ns
				4	4.04	4.32	ns
				5	3.88	4.24	ns
				6	4.72	5.09	ns
				7	5.47	5.94	ns
				8	5.97	6.52	ns
			1	XC3S200A	2.05	2.20	ns
				2	2.72	2.93	ns
				3	3.38	3.78	ns
				4	3.88	4.37	ns
				5	3.69	4.20	ns
				6	4.56	5.23	ns
				7	5.34	6.11	ns
				8	5.85	6.71	ns
			1	XC3S400A	1.79	2.02	ns
				2	2.43	2.67	ns
				3	3.02	3.43	ns
				4	3.49	3.96	ns
				5	3.41	3.95	ns
				6	4.20	4.81	ns
				7	4.96	5.66	ns
				8	5.44	6.19	ns



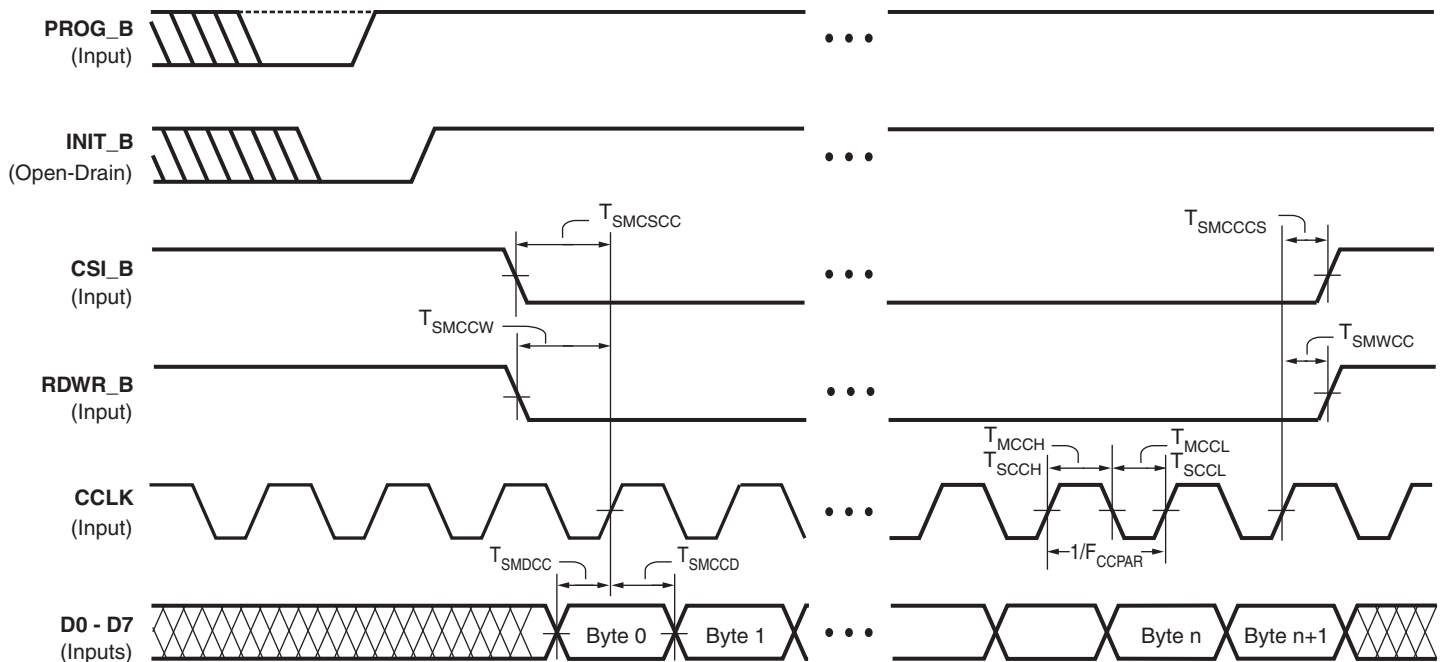
Table 26: Output Timing Adjustments for IOB(Continued)

Convert Output Time from LVC MOS25 with 12mA Drive and Fast Slew Rate to the Following Signal Standard (IOSTANDARD)	Add the Adjustment Below		Units
	Speed Grade		
	-5	-4	
<b>Differential Standards</b>			
LVDS_25	1.16	1.16	ns
LVDS_33	0.46	0.46	ns
BLVDS_25	0.11	0.11	ns
MINI_LVDS_25	0.75	0.75	ns
MINI_LVDS_33	0.40	0.40	ns
LVPECL_25	Input Only		
LVPECL_33			
RS DS_25	1.42	1.42	ns
RS DS_33	0.58	0.58	ns
TMDS_33	0.46	0.46	ns
PPDS_25	1.07	1.07	ns
PPDS_33	0.63	0.63	ns
DIFF_HSTL_I_18	0.43	0.43	ns
DIFF_HSTL_II_18	0.41	0.41	ns
DIFF_HSTL_III_18	0.36	0.36	ns
DIFF_HSTL_I	1.01	1.01	ns
DIFF_HSTL_III	0.54	0.54	ns
DIFF_SSTL18_I	0.49	0.49	ns
DIFF_SSTL18_II	0.41	0.41	ns
DIFF_SSTL2_I	0.82	0.82	ns
DIFF_SSTL2_II	0.09	0.09	ns
DIFF_SSTL3_I	1.16	1.16	ns
DIFF_SSTL3_II	0.28	0.28	ns

**Notes:**

1. The numbers in this table are tested using the methodology presented in Table 27 and are based on the operating conditions set forth in Table 8, Table 11, and Table 13.
2. These adjustments are used to convert output- and three-state-path times originally specified for the LVC MOS25 standard with 12 mA drive and Fast slew rate to times that correspond to other signal standards. Do not adjust times that measure when outputs go into a high-impedance state.
3. Note that 16 mA drive is faster than 24 mA drive for the Slow slew rate.

### Slave Parallel Mode Timing



DS529-3\_02\_051607

**Notes:**

1. It is possible to abort configuration by pulling CSI\_B Low in a given CCLK cycle, then switching RDWR\_B Low or High in any subsequent cycle for which CSI\_B remains Low. The RDWR\_B pin asynchronously controls the driver impedance of the D0 - D7 bus. When RDWR\_B switches High, be careful to avoid contention on the D0 - D7 bus.
2. To pause configuration, pause CCLK instead of de-asserting CSI\_B. See [UG332](#) Chapter 7 section “Non-Continuous SelectMAP Data Loading” for more details.

Figure 13: Waveforms for Slave Parallel Configuration

Table 51: Timing for the Slave Parallel Configuration Mode

Symbol	Description	All Speed Grades		Units	
		Min	Max		
<b>Setup Times</b>					
$T_{SMDCC}^{(2)}$	The time from the setup of data at the D0-D7 pins to the rising transition at the CCLK pin	7	–	ns	
$T_{SMCSCC}$	Setup time on the CSI_B pin before the rising transition at the CCLK pin	7	–	ns	
$T_{SMCCW}$	Setup time on the RDWR_B pin before the rising transition at the CCLK pin	15	–	ns	
<b>Hold Times</b>					
$T_{SMCCD}$	The time from the rising transition at the CCLK pin to the point when data is last held at the D0-D7 pins	1.0	–	ns	
$T_{SMCCCS}$	The time from the rising transition at the CCLK pin to the point when a logic level is last held at the CSO_B pin	0	–	ns	
$T_{SMWCC}$	The time from the rising transition at the CCLK pin to the point when a logic level is last held at the RDWR_B pin	0	–	ns	
<b>Clock Timing</b>					
$T_{CCH}$	The High pulse width at the CCLK input pin	5	–	ns	
$T_{CCL}$	The Low pulse width at the CCLK input pin	5	–	ns	
$F_{CCPAR}$	Frequency of the clock signal at the CCLK input pin	No bitstream compression	0	80	MHz
		With bitstream compression	0	80	MHz

**Notes:**

1. The numbers in this table are based on the operating conditions set forth in [Table 8](#).
2. Some Xilinx documents refer to Parallel modes as “SelectMAP” modes.

IEEE 1149.1/1532 JTAG Test Access Port Timing

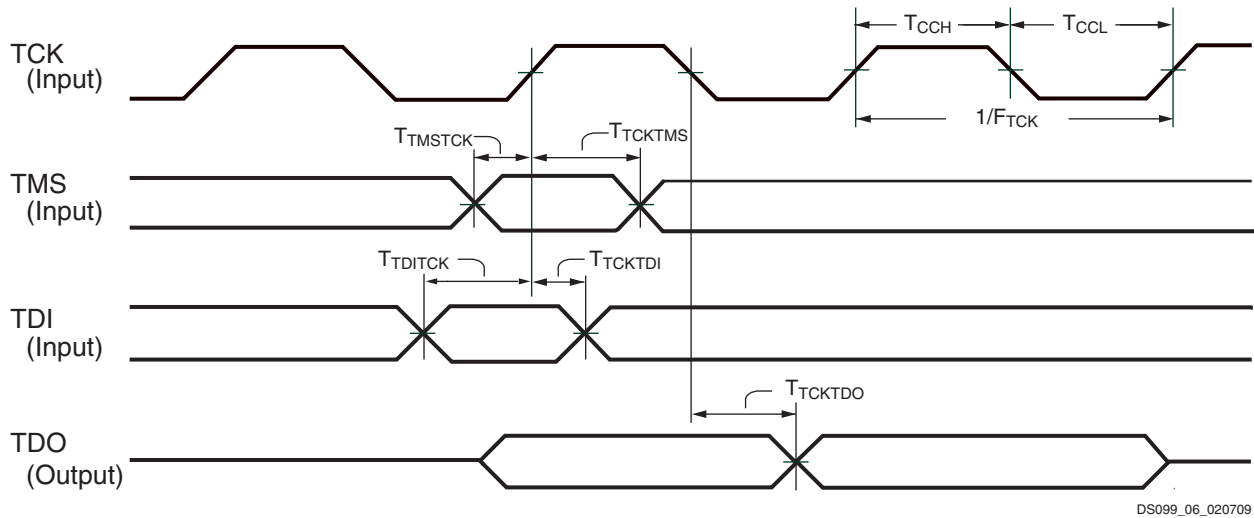


Figure 16: JTAG Waveforms

Table 56: Timing for the JTAG Test Access Port

Symbol	Description	All Speed Grades		Units	
		Min	Max		
<b>Clock-to-Output Times</b>					
T <sub>TCKTDO</sub>	The time from the falling transition on the TCK pin to data appearing at the TDO pin	1.0	11.0	ns	
<b>Setup Times</b>					
T <sub>TDITCK</sub>	The time from the setup of data at the TDI pin to the rising transition at the TCK pin	All devices and functions except those shown below	7.0	–	ns
		Boundary scan commands (INTEST, EXTEST, SAMPLE) on XC3S700A and XC3S1400A FPGAs	11.0		
T <sub>TMSTCK</sub>	The time from the setup of a logic level at the TMS pin to the rising transition at the TCK pin	7.0	–	ns	
<b>Hold Times</b>					
T <sub>TCKTDI</sub>	The time from the rising transition at the TCK pin to the point when data is last held at the TDI pin	All functions except those shown below	0	–	ns
		Configuration commands (CFG_IN, ISC_PROGRAM)	2.0		
T <sub>TCKTMS</sub>	The time from the rising transition at the TCK pin to the point when a logic level is last held at the TMS pin	0	–	ns	
<b>Clock Timing</b>					
T <sub>CCH</sub>	The High pulse width at the TCK pin	All functions except ISC_DNA command	5	–	ns
T <sub>CCL</sub>	The Low pulse width at the TCK pin		5	–	ns
T <sub>CCHDNA</sub>	The High pulse width at the TCK pin	During ISC_DNA command	10	10,000	ns
T <sub>CCLDNA</sub>	The Low pulse width at the TCK pin		10	10,000	ns
F <sub>TCK</sub>	Frequency of the TCK signal	All operations on XC3S50A, XC3S200A, and XC3S400A FPGAs and for BYPASS or HIGHZ instructions on all FPGAs	0	33	MHz
		All operations on XC3S700A and XC3S1400A FPGAs, except for BYPASS or HIGHZ instructions		20	

Notes:

1. The numbers in this table are based on the operating conditions set forth in Table 8.
2. For details on JTAG see Chapter 9 “JTAG Configuration Mode and Boundary-Scan” in UG332 Spartan-3 Generation Configuration User Guide.

## Package Overview

Table 60 shows the six low-cost, space-saving production package styles for the Spartan-3A family.

Table 60: Spartan-3A Family Package Options

Package	Leads	Type	Maximum I/O	Lead Pitch (mm)	Body Area (mm)	Height (mm)	Mass <sup>(1)</sup> (g)
VQ100 / VQG100	100	Very Thin Quad Flat Pack (VQFP)	68	0.5	14 x 14	1.20	0.6
TQ144 / TQG144	144	Thin Quad Flat Pack (TQFP)	108	0.5	20 x 20	1.60	1.4
FT256 / FTG256	256	Fine-pitch Thin Ball Grid Array (FBGA)	195	1.0	17 x 17	1.55	0.9
FG320 / FGG320	320	Fine-pitch Ball Grid Array (FBGA)	251	1.0	19 x 19	2.00	1.4
FG400 / FGG400	400	Fine-pitch Ball Grid Array (FBGA)	311	1.0	21 x 21	2.43	2.2
FG484 / FGG484	484	Fine-pitch Ball Grid Array (FBGA)	375	1.0	23 x 23	2.60	2.2
FG676 / FGG676	676	Fine-pitch Ball Grid Array (FBGA)	502	1.0	27 x 27	2.60	3.4

### Notes:

1. Package mass is  $\pm 10\%$ .

Each package style is available in an environmentally friendly lead-free (Pb-free) option. The Pb-free packages include an extra 'G' in the package style name. For example, the standard "CS484" package becomes "CSG484" when ordered as the Pb-free option. The mechanical dimensions of the standard and Pb-free packages are similar, as shown in the mechanical drawings provided in Table 61.

For additional package information, see [UG112: Device Package User Guide](#).

## Mechanical Drawings

Detailed mechanical drawings for each package type are available from the Xilinx web site at the specified location in Table 61.

Material Declaration Data Sheets (MDDS) are also available on the [Xilinx web site](#) for each package.

Table 61: Xilinx Package Documentation

Package	Drawing	MDDS
VQ100	<a href="#">Package Drawing</a>	<a href="#">PK173_VQ100</a>
VQG100		<a href="#">PK130_VQG100</a>
TQ144	<a href="#">Package Drawing</a>	<a href="#">PK169_TQ144</a>
TQG144		<a href="#">PK126_TQG144</a>
FT256	<a href="#">Package Drawing</a>	<a href="#">PK158_FT256</a>
FTG256		<a href="#">PK115_FTG256</a>
FG320	<a href="#">Package Drawing</a>	<a href="#">PK152_FG320</a>
FGG320		<a href="#">PK106_FGG320</a>
FG400	<a href="#">Package Drawing</a>	<a href="#">PK182_FG400</a>
FGG400		<a href="#">PK108_FGG400</a>
FG484	<a href="#">Package Drawing</a>	<a href="#">PK183_FG484</a>
FGG484		<a href="#">PK110_FGG484</a>
FG676	<a href="#">Package Drawing</a>	<a href="#">PK155_FG676</a>
FGG676		<a href="#">PK111_FGG676</a>

Table 68: Spartan-3A FT256 Pinout (XC3S50A, XC3S200A, XC3S400) (Continued)

Bank	XC3S50A	XC3S200A XC3S400A	FT256 Ball	Type
3	IO_L14N_3/ LHCLK5	IO_L14N_3/ LHCLK5	J1	LHCLK
3	IO_L14P_3/ LHCLK4	IO_L14P_3/ LHCLK4	J2	LHCLK
3	IO_L15N_3/ LHCLK7	IO_L15N_3/ LHCLK7	K1	LHCLK
3	IO_L15P_3/ TRDY2/LHCLK6	IO_L15P_3/ TRDY2/LHCLK6	K3	LHCLK
3	N.C. (◆)	IO_L16N_3	L2	I/O
3	N.C. (◆)	IO_L16P_3/ VREF_3	L1	VREF
3	N.C. (◆)	IO_L17N_3	J6	I/O
3	N.C. (◆)	IO_L17P_3	J4	I/O
3	N.C. (◆)	IO_L18N_3	L3	I/O
3	N.C. (◆)	IO_L18P_3	K4	I/O
3	N.C. (◆)	IO_L19N_3	L4	I/O
3	N.C. (◆)	IO_L19P_3	M3	I/O
3	IO_L20N_3	IO_L20N_3	N1	I/O
3	IO_L20P_3	IO_L20P_3	M1	I/O
3	IO_L22N_3	IO_L22N_3	P1	I/O
3	IO_L22P_3	IO_L22P_3	N2	I/O
3	IO_L23N_3	IO_L23N_3	P2	I/O
3	IO_L23P_3	IO_L23P_3	R1	I/O
3	IO_L24N_3	IO_L24N_3	M4	I/O
3	IO_L24P_3	IO_L24P_3	N3	I/O
3	IP_L04N_3/ VREF_3	IP_L04N_3/ VREF_3	F4	VREF
3	IP_L04P_3	IP_L04P_3	E4	INPUT
3	N.C. (◆)	IP_L06N_3/ VREF_3	G5	VREF
3	N.C. (◆)	IP_L06P_3	G6	INPUT
3	IP_L13N_3	IP_L13N_3	J7	INPUT
3	IP_L13P_3	IP_L13P_3	H7	INPUT
3	IP_L21N_3	IP_L21N_3	K6	INPUT
3	IP_L21P_3	IP_L21P_3	K5	INPUT
3	IP_L25N_3/ VREF_3	IP_L25N_3/ VREF_3	L6	VREF
3	IP_L25P_3	IP_L25P_3	L5	INPUT
3	VCCO_3	VCCO_3	D2	VCCO
3	VCCO_3	VCCO_3	H2	VCCO
3	VCCO_3	VCCO_3	J5	VCCO
3	VCCO_3	VCCO_3	M2	VCCO
GND	GND	GND	A1	GND
GND	GND	GND	A16	GND
GND	GND	GND	B7	GND

Table 68: Spartan-3A FT256 Pinout (XC3S50A, XC3S200A, XC3S400) (Continued)

Bank	XC3S50A	XC3S200A XC3S400A	FT256 Ball	Type
GND	GND	GND	B11	GND
GND	GND	GND	C3	GND
GND	GND	GND	C14	GND
GND	GND	GND	E5	GND
GND	GND	GND	E12	GND
GND	GND	GND	F2	GND
GND	GND	GND	F6	GND
GND	GND	GND	G8	GND
GND	GND	GND	G10	GND
GND	GND	GND	G15	GND
GND	GND	GND	H9	GND
GND	GND	GND	J8	GND
GND	GND	GND	K2	GND
GND	GND	GND	K7	GND
GND	GND	GND	K9	GND
GND	GND	GND	L11	GND
GND	GND	GND	L15	GND
GND	GND	GND	M5	GND
GND	GND	GND	M12	GND
GND	GND	GND	P3	GND
GND	GND	GND	P14	GND
GND	GND	GND	R6	GND
GND	GND	GND	R10	GND
GND	GND	GND	T1	GND
GND	GND	GND	T16	GND
VCCAUX	SUSPEND	SUSPEND	R16	PWR MGMT
VCCAUX	DONE	DONE	T15	CONFIG
VCCAUX	PROG_B	PROG_B	A2	CONFIG
VCCAUX	TCK	TCK	A15	JTAG
VCCAUX	TDI	TDI	B1	JTAG
VCCAUX	TDO	TDO	B16	JTAG
VCCAUX	TMS	TMS	B2	JTAG
VCCAUX	VCCAUX	VCCAUX	E11	VCCAUX
VCCAUX	VCCAUX	VCCAUX	F5	VCCAUX
VCCAUX	VCCAUX	VCCAUX	L12	VCCAUX
VCCAUX	VCCAUX	VCCAUX	M6	VCCAUX
VCCINT	VCCINT	VCCINT	G7	VCCINT
VCCINT	VCCINT	VCCINT	G9	VCCINT
VCCINT	VCCINT	VCCINT	H8	VCCINT
VCCINT	VCCINT	VCCINT	J9	VCCINT

Table 77: Spartan-3A FG320 Pinout(Continued)

Bank	Pin Name	FG320 Ball	Type
0	IP_0	F12	INPUT
0	IP_0	G7	INPUT
0	IP_0	G8	INPUT
0	IP_0	G9	INPUT
0	IP_0	G11	INPUT
0	IP_0/VREF_0	E10	VREF
0	VCCO_0	B5	VCCO
0	VCCO_0	B14	VCCO
0	VCCO_0	D11	VCCO
0	VCCO_0	E8	VCCO
1	IO_L01N_1/LDC2	T17	DUAL
1	IO_L01P_1/HDC	R16	DUAL
1	IO_L02N_1/LDC0	U18	DUAL
1	IO_L02P_1/LDC1	U17	DUAL
1	IO_L03N_1/A1	R17	DUAL
1	IO_L03P_1/A0	T18	DUAL
1	IO_L05N_1	N16	I/O
1	IO_L05P_1	P16	I/O
1	IO_L06N_1	M14	I/O
1	IO_L06P_1	N15	I/O
1	IO_L07N_1/VREF_1	P18	VREF
1	IO_L07P_1	R18	I/O
1	IO_L09N_1/A3	M17	DUAL
1	IO_L09P_1/A2	M16	DUAL
1	IO_L10N_1/A5	N18	DUAL
1	IO_L10P_1/A4	N17	DUAL
1	IO_L11N_1/A7	L12	DUAL
1	IO_L11P_1/A6	L13	DUAL
1	IO_L13N_1/A9	K16	DUAL
1	IO_L13P_1/A8	L17	DUAL
1	IO_L14N_1/RHCLK1	K17	RHCLK
1	IO_L14P_1/RHCLK0	L18	RHCLK
1	IO_L15N_1/TRDY1/RHCLK3	J17	RHCLK
1	IO_L15P_1/RHCLK2	K18	RHCLK
1	IO_L17N_1/RHCLK5	K15	RHCLK
1	IO_L17P_1/RHCLK4	J16	RHCLK
1	IO_L18N_1/RHCLK7	H17	RHCLK
1	IO_L18P_1/IRDY1/RHCLK6	H18	RHCLK
1	IO_L19N_1/A11	G16	DUAL
1	IO_L19P_1/A10	H16	DUAL

Table 77: Spartan-3A FG320 Pinout(Continued)

Bank	Pin Name	FG320 Ball	Type
1	IO_L21N_1	F17	I/O
1	IO_L21P_1	G17	I/O
1	IO_L22N_1/A13	E18	DUAL
1	IO_L22P_1/A12	F18	DUAL
1	IO_L23N_1/A15	H15	DUAL
1	IO_L23P_1/A14	J14	DUAL
1	IO_L25N_1	D17	I/O
1	IO_L25P_1	D18	I/O
1	IO_L26N_1/A17	E16	DUAL
1	IO_L26P_1/A16	F16	DUAL
1	IO_L27N_1/A19	F15	DUAL
1	IO_L27P_1/A18	G15	DUAL
1	IO_L29N_1/A21	E15	DUAL
1	IO_L29P_1/A20	D16	DUAL
1	IO_L30N_1/A23	B18	DUAL
1	IO_L30P_1/A22	C18	DUAL
1	IO_L31N_1/A25	B17	DUAL
1	IO_L31P_1/A24	C17	DUAL
1	IP_L04N_1/VREF_1	N14	VREF
1	IP_L04P_1	P15	INPUT
1	IP_L08N_1/VREF_1	L14	VREF
1	IP_L08P_1	M13	INPUT
1	IP_L12N_1	L16	INPUT
1	IP_L12P_1/VREF_1	M15	VREF
1	IP_L16N_1	K14	INPUT
1	IP_L16P_1	K13	INPUT
1	IP_L20N_1	J13	INPUT
1	IP_L20P_1/VREF_1	K12	VREF
1	IP_L24N_1	G14	INPUT
1	IP_L24P_1	H13	INPUT
1	IP_L28N_1	G13	INPUT
1	IP_L28P_1/VREF_1	H12	VREF
1	IP_L32N_1	F13	INPUT
1	IP_L32P_1/VREF_1	F14	VREF
1	VCCO_1	E17	VCCO
1	VCCO_1	H14	VCCO
1	VCCO_1	L15	VCCO
1	VCCO_1	P17	VCCO
2	IO_L01N_2/M0	U3	DUAL
2	IO_L01P_2/M1	T3	DUAL

# FG320 Footprint

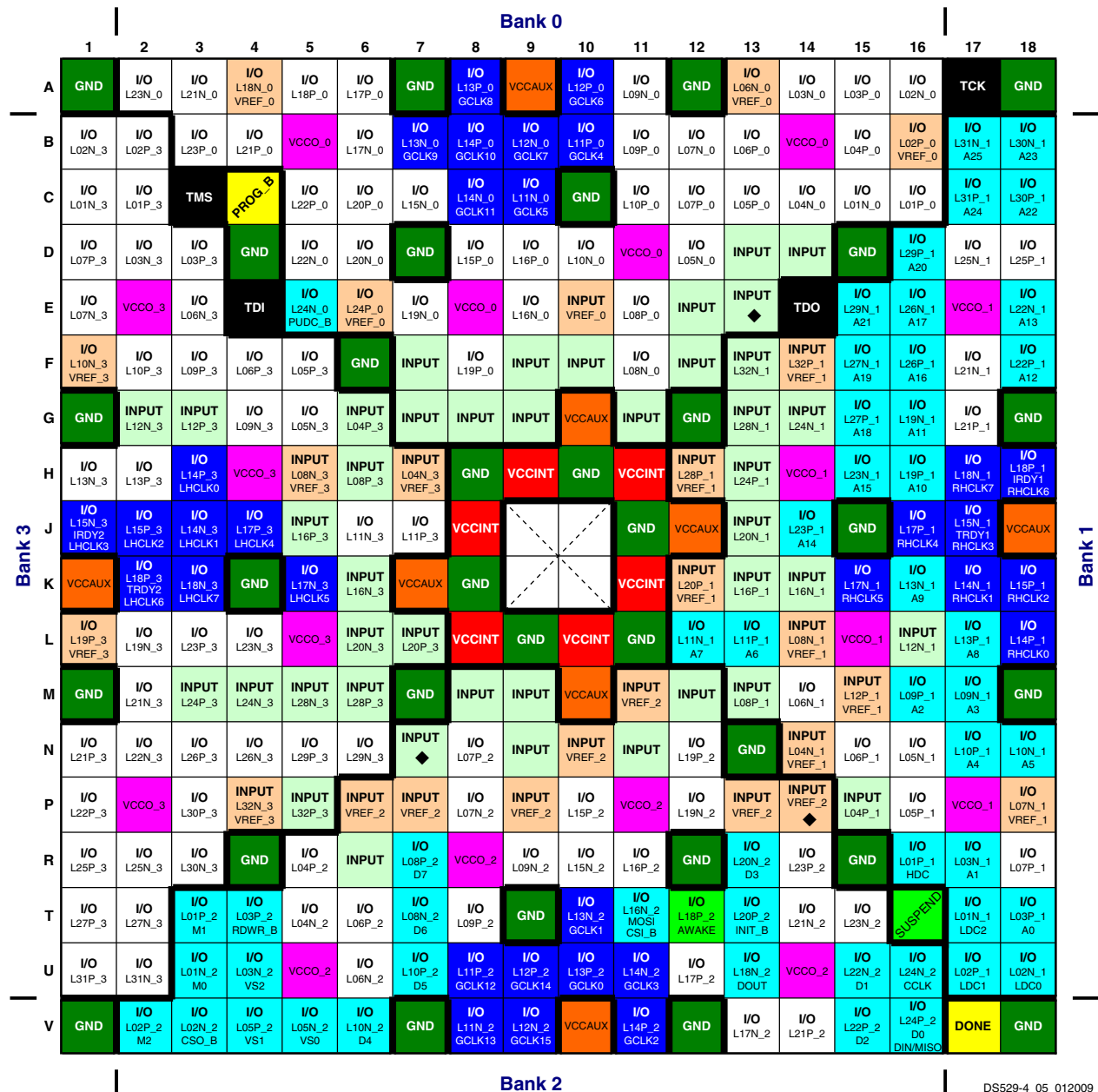


Figure 23: FG320 Package Footprint (Top View)

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- |         |   |    |   |         |   |   |  |
|---------|---|----|---|---------|---|---|--|
| 101     | <b>I/O:</b> Unrestricted, general-purpose user I/O                | 51 | <b>DUAL:</b> Configuration pins, then possible user-I/O | 23 - 24 | <b>VREF:</b> User I/O or input voltage reference for bank | 2 | <b>SUSPEND:</b> Dedicated SUSPEND and dual-purpose AWAKE Power Management pins |
| 40 - 42 | <b>INPUT:</b> Unrestricted, general-purpose input pin             | 32 | <b>CLK:</b> User I/O, input, or global buffer input     | 16      | <b>VCCO:</b> Output voltage supply for bank               |   |  |
| 2       | <b>CONFIG:</b> Dedicated configuration pins                       | 4  | <b>JTAG:</b> Dedicated JTAG port pins                   | 6       | <b>VCCINT:</b> Internal core supply voltage (+1.2V)       |   |  |
| 3       | <b>N.C.:</b> Not connected. Only the XC3S200A has these pins (◆). | 32 | <b>GND:</b> Ground                                      | 8       | <b>VCCAUX:</b> Auxiliary supply voltage                   |   |  |

Bank 0										A
11	12	13	14	15	16	17	18	19	20	
GND	I/O L13N_0	VCCAUX	I/O L07N_0	I/O L08N_0	I/O L05N_0	I/O L04N_0	I/O L01N_0	TCK	GND	B
I/O L14P_0	I/O L13P_0	I/O L11P_0	GND	I/O L08P_0	VCCO_0	I/O L04P_0 VREF_0	I/O L01P_0	I/O L38N_1 A25	I/O L38P_1 A24	C
I/O L14N_0	I/O L11N_0	I/O L10N_0 VREF_0	I/O L07P_0	I/O L06N_0	I/O L05P_0	I/O L02N_0	GND	I/O L37N_1 A23	I/O L37P_1 A22	D
I/O L15P_0 GCLK4	I/O L12P_0	VCCO_0	I/O L10P_0	I/O L06P_0	I/O L03P_0	I/O L02P_0 VREF_0	I/O L34N_1	VCCO_1	I/O L34P_1	E
I/O L15N_0 GCLK5	GND	I/O L09P_0	INPUT	I/O L03N_0	VCCAUX	TDO	I/O L33P_1	I/O L32N_1	I/O L32P_1	F
INPUT	I/O L12N_0	I/O L09N_0	INPUT	GND	I/O L36N_1 A21	I/O L33N_1	I/O L30N_1 A19	I/O L29N_1 A17	I/O L29P_1 A16	G
INPUT VREF_0	INPUT	INPUT	INPUT L39N_1	INPUT L39P_1 VREF_1	I/O L36P_1 A20	I/O L30P_1 A18	I/O L28P_1	GND	I/O L26N_1 A15	H
INPUT	INPUT	GND	INPUT L35N_1	INPUT L35P_1	VCCO_1	I/O L28N_1	I/O L25N_1 A13	I/O L25P_1 A12	I/O L26P_1 A14	J
GND	VCCINT	INPUT L31N_1	INPUT L31P_1 VREF_1	INPUT L27N_1	INPUT L27P_1	I/O L24P_1	I/O L22N_1 A11	I/O L22P_1 A10	I/O L21N_1 RHCLK7	K
VCCINT	GND	VCCAUX	INPUT L23N_1	INPUT L23P_1 VREF_1	I/O L24N_1	GND	I/O L20P_1 RHCLK4	VCCO_1	I/O L21P_1 IRDY1 RHCLK6	L
GND	VCCINT	INPUT L19N_1	INPUT L19P_1	I/O L16P_1 A8	I/O L16N_1 A9	I/O L20N_1 RHCLK5	I/O L18N_1 TRDY1 RHCLK3	I/O L18P_1 RHCLK2	GND	M
VCCINT	GND	INPUT L15N_1	INPUT L15P_1 VREF_1	INPUT L11N_1 VREF_1	INPUT L11P_1	I/O L14P_1 A6	I/O L14N_1 A7	I/O L17P_1 RHCLK0	I/O L17N_1 RHCLK1	N
GND	INPUT VREF_2	GND	INPUT VREF_1	I/O L12P_1 A2	VCCO_1	I/O L12N_1 A3	I/O L13P_1 A4	I/O L13N_1 A5	VCCAUX	P
INPUT VREF_2	INPUT	INPUT	INPUT L04P_1	INPUT L04N_1 VREF_1	I/O L07P_1	I/O L07N_1	I/O L10P_1	GND	I/O L10N_1 VREF_1	R
VCCO_2	I/O L19N_2	I/O L23N_2	INPUT VREF_2	SUSPEND	I/O L03N_1 A1	I/O L08N_1	I/O L08P_1	I/O L09P_1	I/O L09N_1	T
INPUT	I/O L19P_2	I/O L23P_2	I/O L25N_2	I/O L27N_2	GND	I/O L03P_1 A0	I/O L05P_1	VCCO_1	I/O L05N_1	U
I/O L18P_2 GCLK2	GND	I/O L22P_2 AWAKE	VCCO_2	I/O L27P_2	I/O L29N_2	I/O L31N_2	I/O L02N_1 LDC0	I/O L06P_1	I/O L06N_1	V
I/O L17N_2 GCLK1	I/O L18N_2 GCLK3	I/O L22N_2 DOUT	I/O L25P_2	I/O L26N_2 D1	I/O L29P_2	I/O L31P_2	GND	I/O L02P_1 LDC1	I/O L01N_1 LDC2	W
VCCO_2	I/O L20N_2 MOSI CSL_B	I/O L21N_2	I/O L24N_2 D3	GND	I/O L28N_2	VCCO_2	I/O L32P_2 D0 DIN/MISO	DONE	I/O L01P_1 HDC	Y
I/O L17P_2 GCLK0	I/O L20P_2	I/O L21P_2	I/O L24P_2 INIT_B	I/O L26P_2 D2	I/O L28P_2	I/O L30P_2	I/O L30N_2	I/O L32N_2 CCLK	GND	

Right Half of FG400 Package (Top View)

Bank 1

Bank 2

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Table 83: Spartan-3A FG484 Pinout(Continued)

Bank	Pin Name	FG484 Ball	Type
0	IO_L30P_0	E9	I/O
0	IO_L31N_0	B4	I/O
0	IO_L31P_0	A4	I/O
0	IO_L32N_0	D5	I/O
0	IO_L32P_0	C5	I/O
0	IO_L33N_0	B3	I/O
0	IO_L33P_0	A3	I/O
0	IO_L34N_0	F8	I/O
0	IO_L34P_0	E7	I/O
0	IO_L35N_0	E6	I/O
0	IO_L35P_0	F7	I/O
0	IO_L36N_0/PUDC_B	A2	DUAL
0	IO_L36P_0/VREF_0	B2	VREF
0	IP_0	E16	INPUT
0	IP_0	E8	INPUT
0	IP_0	F10	INPUT
0	IP_0	F12	INPUT
0	IP_0	F16	INPUT
0	IP_0	G10	INPUT
0	IP_0	G11	INPUT
0	IP_0	G12	INPUT
0	IP_0	G13	INPUT
0	IP_0	G14	INPUT
0	IP_0	G15	INPUT
0	IP_0	G16	INPUT
0	IP_0	G7	INPUT
0	IP_0	G9	INPUT
0	IP_0	H10	INPUT
0	IP_0	H13	INPUT
0	IP_0	H14	INPUT
0	IP_0/VREF_0	G8	VREF
0	IP_0/VREF_0	H12	VREF
0	IP_0/VREF_0	H9	VREF
0	VCCO_0	B10	VCCO
0	VCCO_0	B14	VCCO
0	VCCO_0	B18	VCCO
0	VCCO_0	B5	VCCO
0	VCCO_0	F14	VCCO
0	VCCO_0	F9	VCCO
1	IO_L01N_1/LDC2	Y21	DUAL

Table 83: Spartan-3A FG484 Pinout(Continued)

Bank	Pin Name	FG484 Ball	Type
1	IO_L01P_1/HDC	AA22	DUAL
1	IO_L02N_1/LDC0	W20	DUAL
1	IO_L02P_1/LDC1	W19	DUAL
1	IO_L03N_1/A1	T18	DUAL
1	IO_L03P_1/A0	T17	DUAL
1	IO_L05N_1	W21	I/O
1	IO_L05P_1	Y22	I/O
1	IO_L06N_1	V20	I/O
1	IO_L06P_1	V19	I/O
1	IO_L07N_1	V22	I/O
1	IO_L07P_1	W22	I/O
1	IO_L09N_1	U21	I/O
1	IO_L09P_1	U22	I/O
1	IO_L10N_1	U19	I/O
1	IO_L10P_1	U20	I/O
1	IO_L11N_1	T22	I/O
1	IO_L11P_1	T20	I/O
1	IO_L13N_1	T19	I/O
1	IO_L13P_1	R20	I/O
1	IO_L14N_1	R22	I/O
1	IO_L14P_1	R21	I/O
1	IO_L15N_1/VREF_1	P22	VREF
1	IO_L15P_1	P20	I/O
1	IO_L17N_1/A3	P18	DUAL
1	IO_L17P_1/A2	R19	DUAL
1	IO_L18N_1/A5	N21	DUAL
1	IO_L18P_1/A4	N22	DUAL
1	IO_L19N_1/A7	N19	DUAL
1	IO_L19P_1/A6	N20	DUAL
1	IO_L20N_1/A9	N17	DUAL
1	IO_L20P_1/A8	N18	DUAL
1	IO_L21N_1/RHCLK1	L22	RHCLK
1	IO_L21P_1/RHCLK0	M22	RHCLK
1	IO_L22N_1/TRDY1/RHCLK3	L20	RHCLK
1	IO_L22P_1/RHCLK2	L21	RHCLK
1	IO_L24N_1/RHCLK5	M20	RHCLK
1	IO_L24P_1/RHCLK4	M18	RHCLK
1	IO_L25N_1/RHCLK7	K19	RHCLK
1	IO_L25P_1/IRDY1/RHCLK6	K20	RHCLK
1	IO_L26N_1/A11	J22	DUAL

Table 83: Spartan-3A FG484 Pinout(Continued)

Bank	Pin Name	FG484 Ball	Type
3	IP_L04P_3	H8	INPUT
3	IP_L11N_3	K8	INPUT
3	IP_L11P_3	J7	INPUT
3	IP_L15N_3/VREF_3	L8	VREF
3	IP_L15P_3	K7	INPUT
3	IP_L19N_3	M8	INPUT
3	IP_L19P_3	L7	INPUT
3	IP_L23N_3	M6	INPUT
3	IP_L23P_3	M7	INPUT
3	IP_L27N_3	N9	INPUT
3	IP_L27P_3	N8	INPUT
3	IP_L31N_3	N5	INPUT
3	IP_L31P_3	N6	INPUT
3	IP_L35N_3	P8	INPUT
3	IP_L35P_3	N7	INPUT
3	IP_L39N_3	R8	INPUT
3	IP_L39P_3	P7	INPUT
3	IP_L46N_3/VREF_3	T6	VREF
3	IP_L46P_3	R7	INPUT
3	VCCO_3	E2	VCCO
3	VCCO_3	J2	VCCO
3	VCCO_3	J6	VCCO
3	VCCO_3	N2	VCCO
3	VCCO_3	P6	VCCO
3	VCCO_3	V2	VCCO
GND	GND	A1	GND
GND	GND	A22	GND
GND	GND	AA11	GND
GND	GND	AA16	GND
GND	GND	AA7	GND
GND	GND	AB1	GND
GND	GND	AB22	GND
GND	GND	B12	GND
GND	GND	B16	GND
GND	GND	B7	GND
GND	GND	C20	GND
GND	GND	C3	GND
GND	GND	D14	GND
GND	GND	D9	GND
GND	GND	F11	GND

Table 83: Spartan-3A FG484 Pinout(Continued)

Bank	Pin Name	FG484 Ball	Type
GND	GND	F17	GND
GND	GND	F6	GND
GND	GND	G2	GND
GND	GND	G21	GND
GND	GND	J11	GND
GND	GND	J13	GND
GND	GND	J14	GND
GND	GND	J19	GND
GND	GND	J4	GND
GND	GND	J9	GND
GND	GND	K10	GND
GND	GND	K12	GND
GND	GND	L11	GND
GND	GND	L13	GND
GND	GND	L17	GND
GND	GND	L2	GND
GND	GND	L6	GND
GND	GND	L9	GND
GND	GND	M10	GND
GND	GND	M12	GND
GND	GND	M14	GND
GND	GND	M21	GND
GND	GND	N11	GND
GND	GND	N13	GND
GND	GND	P10	GND
GND	GND	P14	GND
GND	GND	P19	GND
GND	GND	P4	GND
GND	GND	P9	GND
GND	GND	T12	GND
GND	GND	T2	GND
GND	GND	T21	GND
GND	GND	U17	GND
GND	GND	U6	GND
GND	GND	W10	GND
GND	GND	W14	GND
GND	GND	Y20	GND
GND	GND	Y3	GND
VCCAUX	SUSPEND	U18	PWR MGMT

## FG676: 676-ball Fine-pitch Ball Grid Array

The 676-ball fine-pitch ball grid array, FG676, supports the XC3S1400A FPGA.

Table 87 lists all the FG676 package pins. They are sorted by bank number and then by pin name. Pairs of pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type, as defined earlier.

The XC3S1400A has 17 unconnected balls, indicated as N.C. (No Connection) in Table 87 and with the black diamond character (◆) in Table 87 and Figure 27.

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at:

[www.xilinx.com/support/documentation/data\\_sheets/s3a\\_pin.zip](http://www.xilinx.com/support/documentation/data_sheets/s3a_pin.zip)

### Pinout Table

Table 87: Spartan-3A FG676 Pinout

Bank	Pin Name	FG676 Ball	Type
0	IO_L01N_0	F20	I/O
0	IO_L01P_0	G20	I/O
0	IO_L02N_0	F19	I/O
0	IO_L02P_0/VREF_0	G19	VREF
0	IO_L05N_0	C22	I/O
0	IO_L05P_0	D22	I/O
0	IO_L06N_0	C23	I/O
0	IO_L06P_0	D23	I/O
0	IO_L07N_0	A22	I/O
0	IO_L07P_0	B23	I/O
0	IO_L08N_0	G17	I/O
0	IO_L08P_0	H17	I/O
0	IO_L09N_0	B21	I/O
0	IO_L09P_0	C21	I/O
0	IO_L10N_0	D21	I/O
0	IO_L10P_0	E21	I/O
0	IO_L11N_0	C20	I/O
0	IO_L11P_0	D20	I/O
0	IO_L12N_0	K16	I/O
0	IO_L12P_0	J16	I/O
0	IO_L13N_0	E17	I/O
0	IO_L13P_0	F17	I/O
0	IO_L14N_0	A20	I/O
0	IO_L14P_0/VREF_0	B20	VREF

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
0	IO_L15N_0	A19	I/O
0	IO_L15P_0	B19	I/O
0	IO_L16N_0	H15	I/O
0	IO_L16P_0	G15	I/O
0	IO_L17N_0	C18	I/O
0	IO_L17P_0	D18	I/O
0	IO_L18N_0	A18	I/O
0	IO_L18P_0	B18	I/O
0	IO_L19N_0	B17	I/O
0	IO_L19P_0	C17	I/O
0	IO_L20N_0/VREF_0	E15	VREF
0	IO_L20P_0	F15	I/O
0	IO_L21N_0	C16	I/O
0	IO_L21P_0	D17	I/O
0	IO_L22N_0	C15	I/O
0	IO_L22P_0	D16	I/O
0	IO_L23N_0	A15	I/O
0	IO_L23P_0	B15	I/O
0	IO_L24N_0	F14	I/O
0	IO_L24P_0	E14	I/O
0	IO_L25N_0/GCLK5	J14	GCLK
0	IO_L25P_0/GCLK4	K14	GCLK
0	IO_L26N_0/GCLK7	A14	GCLK
0	IO_L26P_0/GCLK6	B14	GCLK
0	IO_L27N_0/GCLK9	G13	GCLK
0	IO_L27P_0/GCLK8	F13	GCLK
0	IO_L28N_0/GCLK11	C13	GCLK
0	IO_L28P_0/GCLK10	B13	GCLK
0	IO_L29N_0	B12	I/O
0	IO_L29P_0	A12	I/O
0	IO_L30N_0	C12	I/O
0	IO_L30P_0	D13	I/O
0	IO_L31N_0	F12	I/O
0	IO_L31P_0	E12	I/O
0	IO_L32N_0/VREF_0	D11	VREF
0	IO_L32P_0	C11	I/O
0	IO_L33N_0	B10	I/O
0	IO_L33P_0	A10	I/O

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
2	IP_2	AD10	INPUT
2	IP_2	AD16	INPUT
2	IP_2	AF2	INPUT
2	IP_2	AF7	INPUT
2	IP_2	Y11	INPUT
2	IP_2/VREF_2	AA9	VREF
2	IP_2/VREF_2	AA20	VREF
2	IP_2/VREF_2	AB6	VREF
2	IP_2/VREF_2	AB10	VREF
2	IP_2/VREF_2	AC10	VREF
2	IP_2/VREF_2	AD12	VREF
2	IP_2/VREF_2	AF15	VREF
2	IP_2/VREF_2	AF17	VREF
2	IP_2/VREF_2	AF22	VREF
2	IP_2/VREF_2	Y16	VREF
2	N.C. (◆)	AA8	N.C.
2	N.C. (◆)	AC5	N.C.
2	N.C. (◆)	AC22	N.C.
2	N.C. (◆)	AD5	N.C.
2	N.C. (◆)	Y18	N.C.
2	N.C. (◆)	Y19	N.C.
2	N.C. (◆)	AD23	N.C.
2	N.C. (◆)	W18	N.C.
2	N.C. (◆)	Y8	N.C.
2	VCCO_2	AB8	VCCO
2	VCCO_2	AB14	VCCO
2	VCCO_2	AB19	VCCO
2	VCCO_2	AE5	VCCO
2	VCCO_2	AE11	VCCO
2	VCCO_2	AE16	VCCO
2	VCCO_2	AE22	VCCO
2	VCCO_2	W11	VCCO
2	VCCO_2	W16	VCCO
3	IO_L01N_3	J9	I/O
3	IO_L01P_3	J8	I/O
3	IO_L02N_3	B1	I/O
3	IO_L02P_3	B2	I/O
3	IO_L03N_3	H7	I/O
3	IO_L03P_3	G6	I/O
3	IO_L05N_3	K8	I/O

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
3	IO_L05P_3	K9	I/O
3	IO_L06N_3	E4	I/O
3	IO_L06P_3	D3	I/O
3	IO_L07N_3	F4	I/O
3	IO_L07P_3	E3	I/O
3	IO_L09N_3	G4	I/O
3	IO_L09P_3	F5	I/O
3	IO_L10N_3	H6	I/O
3	IO_L10P_3	J7	I/O
3	IO_L11N_3	F2	I/O
3	IO_L11P_3	E1	I/O
3	IO_L13N_3	J6	I/O
3	IO_L13P_3	K7	I/O
3	IO_L14N_3	F3	I/O
3	IO_L14P_3	G3	I/O
3	IO_L15N_3	L9	I/O
3	IO_L15P_3	L10	I/O
3	IO_L17N_3	H1	I/O
3	IO_L17P_3	H2	I/O
3	IO_L18N_3	L7	I/O
3	IO_L18P_3	K6	I/O
3	IO_L19N_3	J4	I/O
3	IO_L19P_3	J5	I/O
3	IO_L21N_3	M9	I/O
3	IO_L21P_3	M10	I/O
3	IO_L22N_3	K4	I/O
3	IO_L22P_3	K5	I/O
3	IO_L23N_3	K2	I/O
3	IO_L23P_3	K3	I/O
3	IO_L25N_3	L3	I/O
3	IO_L25P_3	L4	I/O
3	IO_L26N_3	M7	I/O
3	IO_L26P_3	M8	I/O
3	IO_L27N_3	M3	I/O
3	IO_L27P_3	M4	I/O
3	IO_L28N_3	M6	I/O
3	IO_L28P_3	M5	I/O
3	IO_L29N_3/VREF_3	M1	VREF
3	IO_L29P_3	M2	I/O
3	IO_L30N_3	N4	I/O

